"Circuits and Systems for Sustainable Development"

ISCAS 2024

Singapore | May 19-22, 2024
Resorts World Sentosa Convention Centre

75 YEARS — CAS

Exhibition & Sponsorship Prospectus

The IEEE International Symposium on Circuits and Systems (ISCAS) is the flagship conference of the IEEE Circuits and Systems Society and the world's premier forum for researchers in the active fields of theory, design and implementation of circuits and systems. ISCAS typically attracts 1000+ attendees from academia, research & industry spread across the globe in the fields of theory, design, and implementation of Circuits & Systems. The theme of ISCAS 2024 is **Circuits and Systems for Sustainable Development** and will be held in Singapore, from May 19 to 22, 2024. This symposium will include technical oral lectures and poster sessions, special sessions, tutorials, live demos and workshops highlighting the following innovation themes:

- *Artificial Intelligence and Deep Learning*
- *Smart Systems for Automotive*
- *Brain: Innovation Neurotechnologies*
- *Intelligent Cyber Security Systems*
- *Food Security and Climate Change*
- *Ultra Low Power Circuits and Systems*

IEEE ISCAS 2024's organizing committee has created a set of sponsorship opportunity packages to provide the best possible *Return on Investment* for your business: **Gold, Platinum, and Diamond**. For more information, please contact our Sponsorship/Exhibition Co-Chairs: Xuanyao Fong (kelvin.xy.fong@nus.edu.sg), Anh Tuan Do (doat@ime.a-star.edu.sg), Zhengguo Li (ezgli@i2r.a-star.edu.sg).

SPONSORSHIP PACKAGES*	Gold	Platinum	Diamond
Amount	$4.5K	$9K	$18K
Maximum available slots	12	5	3
Number of full registrations included	1	2	4
Complementary registration to industry program, gala dinner and tutorial		3	7
One exhibition booth	✔	✔	✔
Listed as exhibitor/promotional sponsor on website & printed materials	✔	✔	✔
Company logo on the final program	✔	✔	✔
Company logo on the welcome sign	✔	✔	✔
Company logo on the website	✔	✔	✔
Company logo on the opening slide of the symposium		✔	✔
Recognition as Sponsor of Technical Session		✔	✔
Recognition as Exclusive Sponsor of workshops/tutorial/live demo		✔	✔
Recognition as Sponsor of Lunch or Gala Dinner			✔
One-minute company video before plenary			✔
Company logo on delegate bag			✔
Access to a meeting room (interviews, hospitality) - reservation needed			✔

* Customized package can be discussed upon request.

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